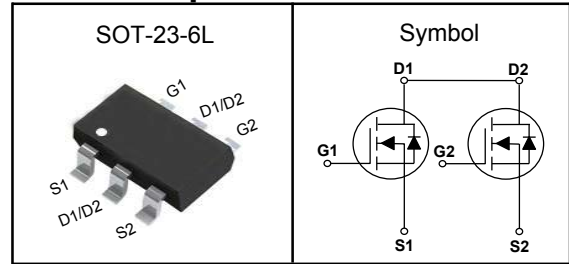


**Common-Drain Dual N-Channel Enhancement Mode MOSFET**
**Features**

- Low  $R_{ds(on)}$  for low conduction loss
- Reliable and Rugged
- ROHS Compliant & Halogen-Free

**Pin Description**

**Applications**

- Power Management in Desktop Computer
- DC/DC Converters

$V_{DSS}$	20	V
$R_{DS(ON)-Typ}$	20	m $\Omega$
$I_D$	6	A

**Absolute Maximum Ratings** ( $T_A=25^\circ\text{C}$ , Unless Otherwise Noted)

Symbol	Parameter	Rating	Unit
$V_{DSS}$	Drain-Source Voltage	20	V
$V_{GSS}$	Gate-Source Voltage	$\pm 20$	V
$T_J$	Maximum Junction Temperature	-55 to 150	$^\circ\text{C}$
$T_{STG}$	Storage Temperature Range	-55 to 150	$^\circ\text{C}$
$I_{DM}^{①}$	Pulse Drain Current Tested	25	A
$I_D$	Continuous Drain Current	6	A
$P_D$	Maximum Power Dissipation	1.25	W

**Thermal Characteristics**

Symbol	Parameter	Rating	Unit
$R_{\theta JA}$	Thermal Resistance-Junction to Ambient	357	$^\circ\text{C/W}$

Note ① : Max. current is limited by bonding wire.

Note ② : UIS tested and pulse width are limited by maximum junction temperature  $150^\circ\text{C}$ .

Note ③ : Surface Mounted on  $1\text{in}^2$  FR-4 board with 1oz.



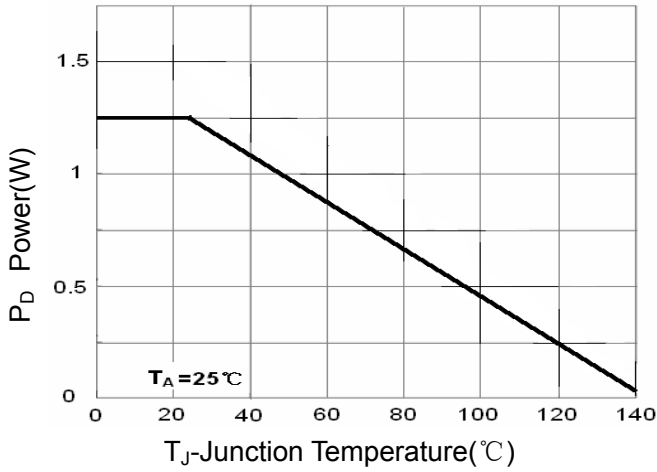
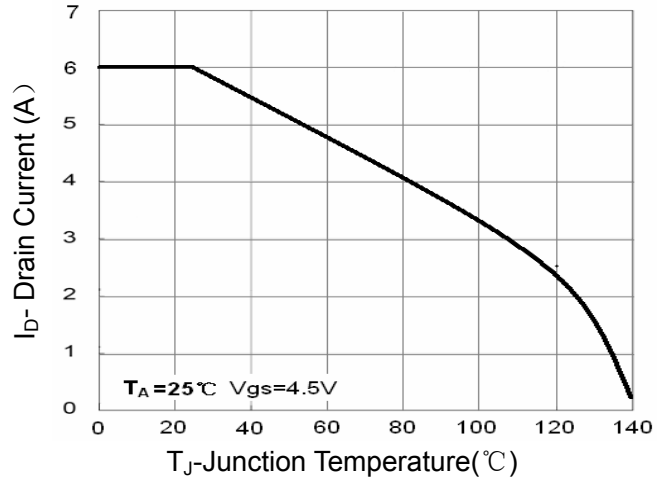
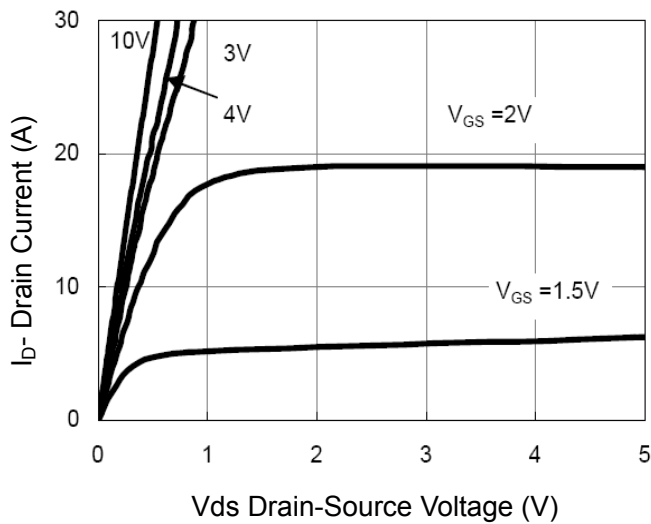
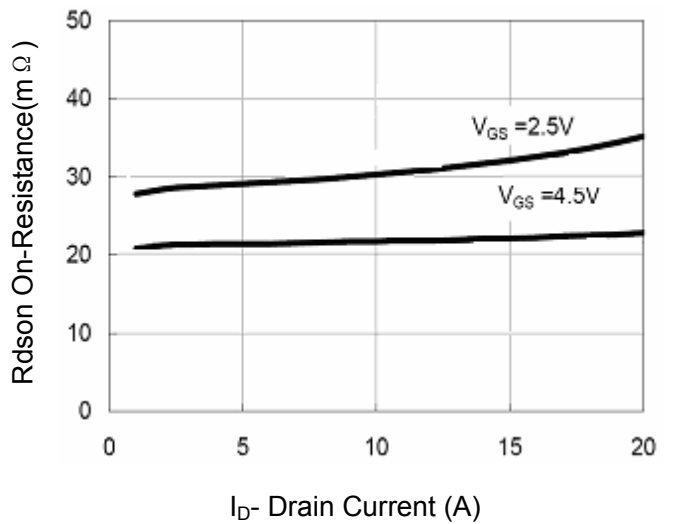
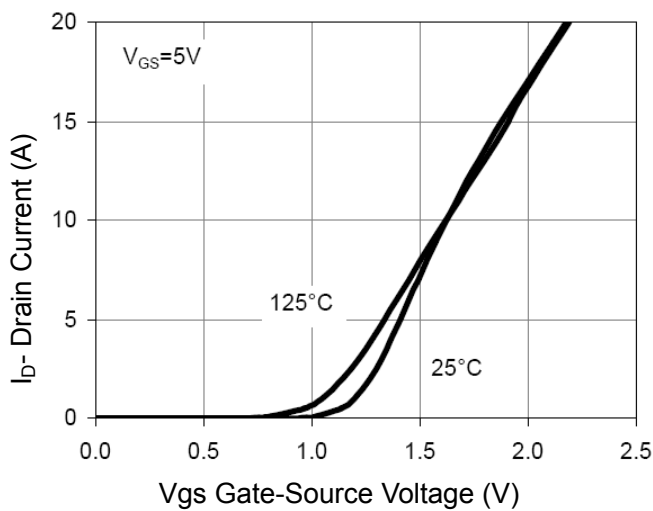
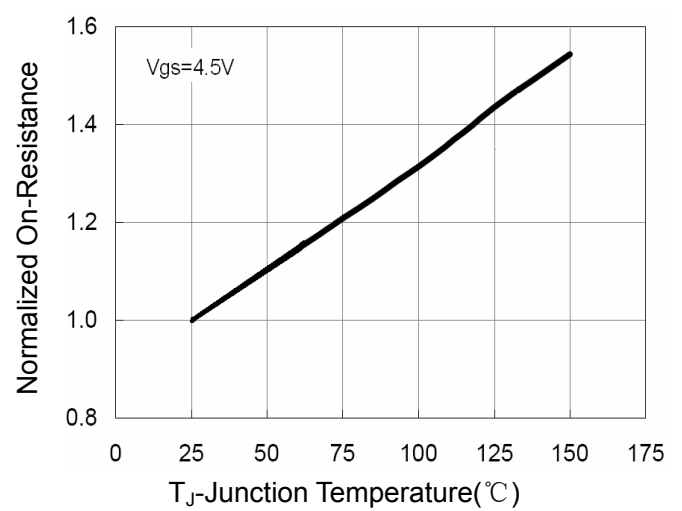
**Common-Drain Dual N-Channel Enhancement Mode MOSFET**

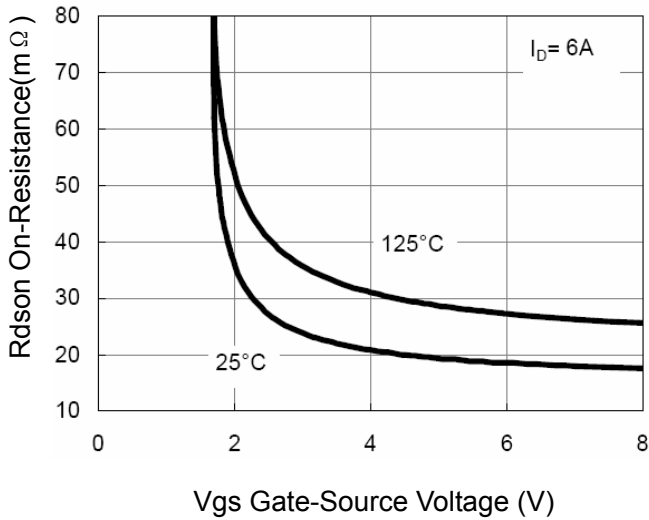
**Electrical Characteristics** ( $T_J=25^{\circ}\text{C}$ , Unless Otherwise Noted)

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
<b>Static Electrical Characteristics</b>						
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	20	---	---	V
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS}=18V, V_{GS}=0V$	---	---	1	$\mu A$
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu A$	0.5	---	0.9	V
$I_{GSS}$	Gate Leakage Current	$V_{GS}=\pm 10V, V_{DS}=0V$	---	---	$\pm 100$	nA
$R_{DS(on)}$	Drain-Source On-state Resistance	$V_{GS}=4.5V, I_D=6A$	---	20	25	$m\Omega$
		$V_{GS}=2.5V, I_D=5A$	---	26	32	$m\Omega$
<b>Dynamic Characteristics<sup>⑤</sup></b>						
$C_{iss}$	Input Capacitance	$V_{GS}=0V, V_{DS}=8V, \text{Freq.}=1\text{MHz}$	---	800	---	pF
$C_{oss}$	Output Capacitance		---	155	---	
$C_{rss}$	Reverse Transfer Capacitance		---	125	---	
$T_{d(on)}$	Turn-on Delay Time	$V_{DD}=10V, V_{GS}=4V, R_G=10\Omega, I_D=1A$	---	18	---	nS
$T_r$	Turn-on Rise Time		---	5	---	
$T_{d(off)}$	Turn-off Delay Time		---	43	---	
$T_f$	Turn-off Fall Time		---	20	---	
$Q_g$	Total Gate Charge	$V_{DS}=10V, V_{GS}=4.5V, I_D=4A$	---	11	---	nC
$Q_{gs}$	Gate-Source Charge		---	2.3	---	
$Q_{gd}$	Gate-Drain Charge		---	2.5	---	
<b>Source-Drain Characteristics (<math>T_J=25^{\circ}\text{C}</math>)</b>						
$V_{SD}^{④}$	Diode Forward Voltage	$I_S=1.25A, V_{GS}=0V$	---	---	1.2	V

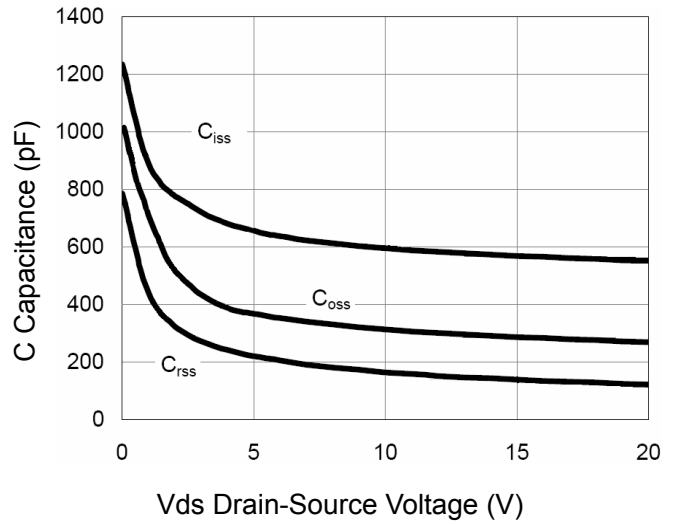
Note ④ : Pulse test (pulse width $\leq 300\mu s$ , duty cycle $\leq 2\%$ ).

Note ⑤ : Guaranteed by design, not subject to production testing.

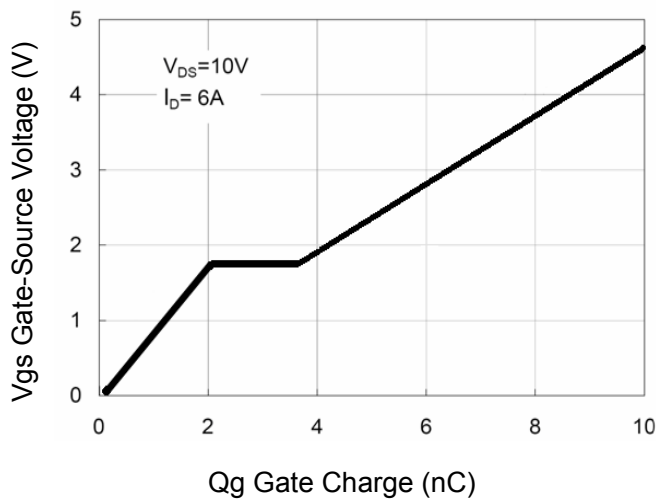
**Common-Drain Dual N-Channel Enhancement Mode MOSFET**
**Typical Characteristics**

**Figure 1 Power Dissipation**

**Figure 2 Drain Current**

**Figure 3 Output Characteristics**

**Figure 4 Drain-Source On-Resistance**

**Figure 5 Transfer Characteristics**

**Figure 6 Drain-Source On-Resistance**

**Common-Drain Dual N-Channel Enhancement Mode MOSFET**


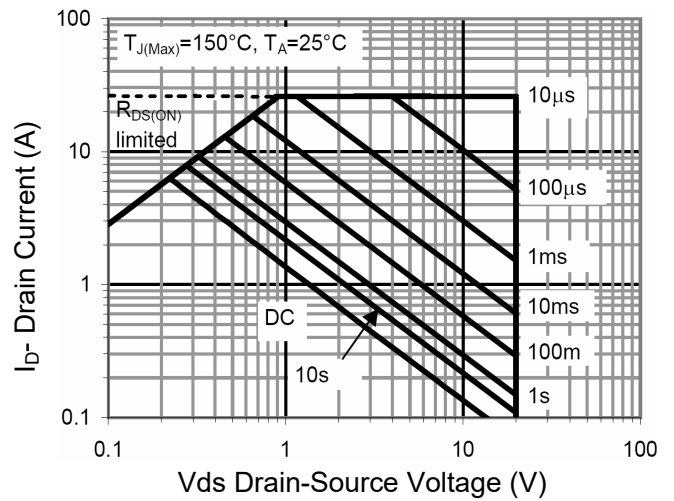
**Figure 7 Rdson vs Vgs**



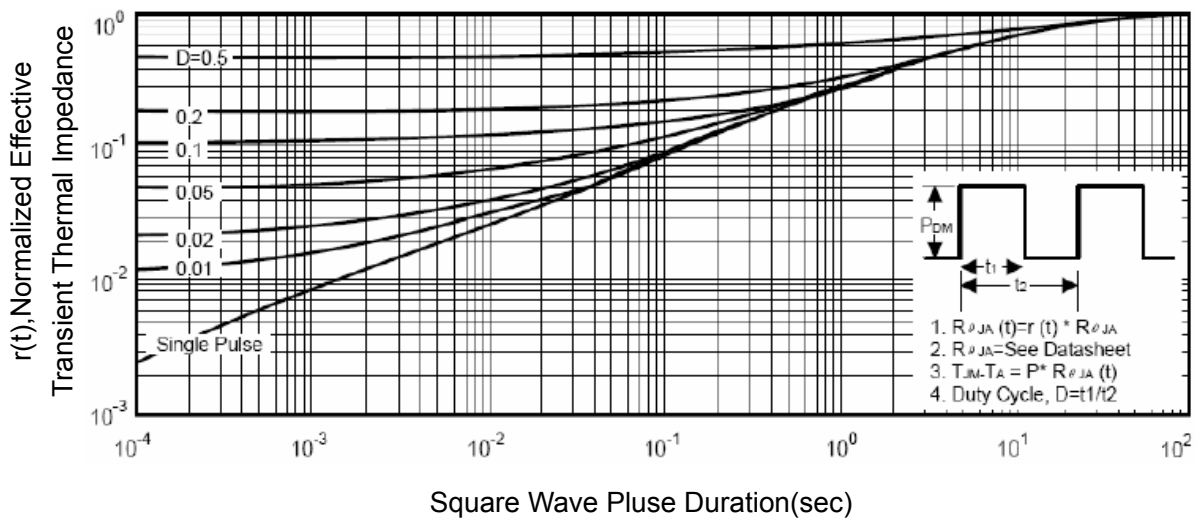
**Figure 8 Capacitance vs Vds**



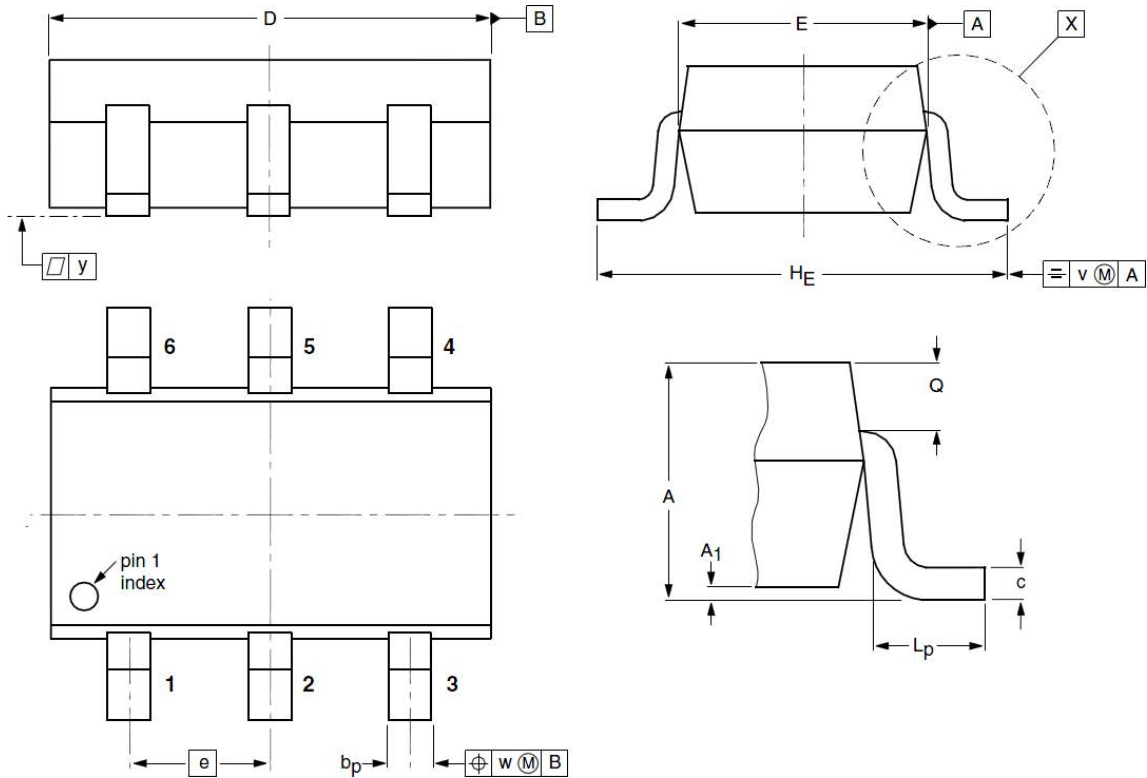
**Figure 9 Gate Charge**



**Figure 10 Safe Operation Area**



**Figure 11 Normalized Maximum Transient Thermal Impedance**

**Common-Drain Dual N-Channel Enhancement Mode MOSFET**
**SOT23-6L Package Outline Dimensions**


Symbol	Dimensions (unit:mm)			Symbol	Dimensions (unit:mm)		
	Min	Typ	Max		Min	Typ	Max
<b>A</b>	0.90	1.07	1.45	<b>A<sub>1</sub></b>	0.01	0.05	0.15
<b>b<sub>p</sub></b>	0.30	0.40	0.50	<b>c</b>	0.10	0.15	0.22
<b>D</b>	2.70	2.92	3.10	<b>E</b>	1.35	1.55	1.75
<b>e</b>	--	0.95	--	<b>H<sub>E</sub></b>	2.50	2.80	3.00
<b>L<sub>p</sub></b>	0.30	0.45	0.60	<b>Q</b>	0.23	0.29	0.33
<b>v</b>	--	0.20	--	<b>W</b>	--	0.20	--
<b>y</b>	--	0.10	--				